# TSCDH30065G1 Taiwan Semiconductor

# 30A, 650V SiC Merged PIN Schottky Diode

## FEATURES

- Max junction temperature 175°C
- MPS structure for high ruggedness to forward current surge events
- High-speed switching possible
- High forward surge capability
- High-frequency operation
- Positive temperature coefficient on VF
- RoHS compliant
- Halogen-free

## APPLICATIONS

- General purpose
- Switch mode power supplies
- Power factor correction

# **MECHANICAL DATA**

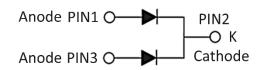
- Case: TO-247-3L
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Polarity: As circuit diagram
- Weight: 6.28g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
lF	30	А	
V <sub>RRM</sub>	650 V		
IFSM	128	А	
T <sub>J MAX</sub>	175 °C		
Package	TO-247-3L		
Configuration	Common cathode		





TO-247-3L



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)				
PARAMETER		SYMBOL	VALUE	UNIT
Repetitive peak reverse voltage		Vrrm	650	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	455	V
Continuous Rectified Forward Current @ T <sub>J</sub> = 159°C per leg / per device		lF	15 / 30	А
Surge peak forward current 10ms single half sine-wave superimposed on rated load	$T_C = 25^{\circ}C$	IFSM	128	Α
	Tc = 125°C		108	Α
Junction temperature		TJ	-55 to +175	°C
Storage temperature		T <sub>STG</sub>	-55 to +175	°C





# rrept



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	ΤΥΡ	MAX	UNIT
Junction-to-case thermal resistance per leg	R <sub>ejc</sub>	0.65	0.78	°C/W

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage per leg <sup>(1)</sup>	$I_F = 7.5A, T_J = 25^{\circ}C$	VF	1.15	-	V
	$I_F = 15A, T_J = 25^{\circ}C$		1.36	1.45	V
	$I_F = 7.5A, T_J = 150^{\circ}C$		1.18	-	V
	$I_F = 15A, T_J = 150^{\circ}C$		1.57	-	V
	$I_F = 7.5A, T_J = 175^{\circ}C$		1.21	-	V
	$I_F = 15A, T_J = 175^{\circ}C$		1.63	1.85	V
Deverse surrent @ roted \/_ per log(2)	$T_J = 25^{\circ}C$		-	20	μA
Reverse current @ rated V <sub>R</sub> per leg <sup>(2)</sup>	T <sub>J</sub> = 175°C	l <sub>R</sub>	-	200	μA
Junction capacitance per leg	$f = 1MHz, V_R = 1V$	CJ	744	-	pF
	$f = 1MHz, V_R = 200V$		114	-	pF
	$f = 1MHz, V_R = 400V$		79	-	pF
Capacitive Charge per leg	V <sub>R</sub> = 400V	Qc	54.4	-	nC

#### Notes:

1. Pulse test with PW = 0.3ms

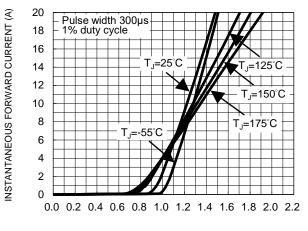
2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
TSCDH30065G1	TO-247-3L	30 / Tube	



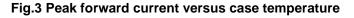
## **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)



**Fig.1 Typical Forward Characteristics** 

FORWARD VOLTAGE (V)



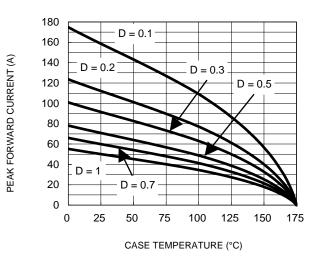
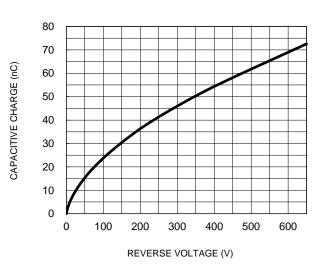
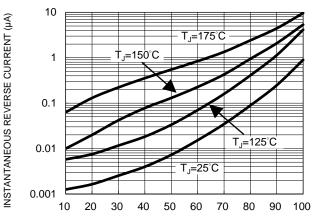
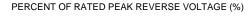


Fig.5 Typical Capacitive Charge





#### Fig.2 Typical Reverse Characteristics



**Fig.4 Typical Junction Capacitance** 

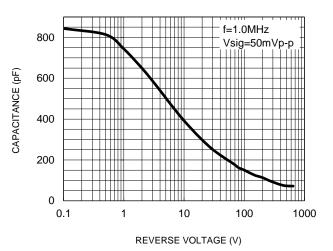
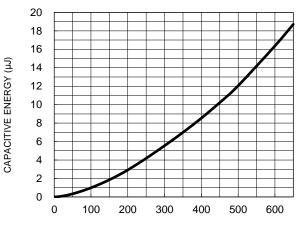


FIG.6 Typical Capacitance Stored Energy

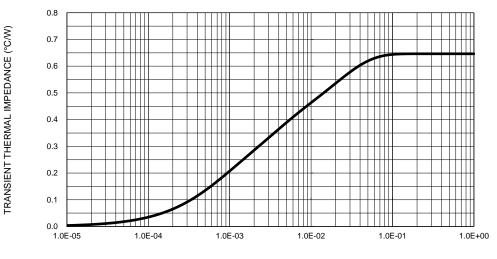


REVERSE VOLTAGE (V)



# **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

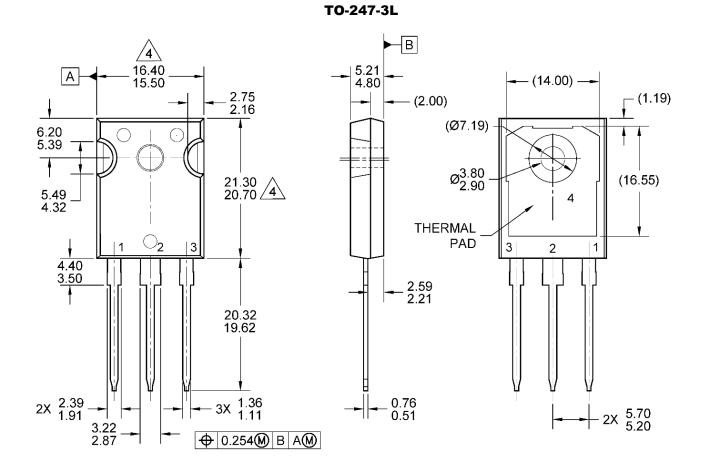


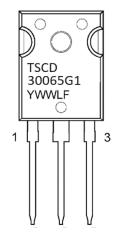
#### Fig.7 Typical Transient Thermal Characteristics

PULSE DURATION (s)



## **PACKAGE OUTLINE DIMENSIONS**





#### MARKING DIAGRAM

- Y = YEAR CODE
- WW = WEEK CODE  $(01 \sim 52)$
- L = LOT CODE (1~9, A~Z)
- F = FACTORY CODE

#### NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC TO-247, VARIATION AD, ISSUE E.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
- 5. DWG NO. REF: HQ2SD07-TO247ADSiC-122 REV A.



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Taiwan Semiconductor

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